

Atty. Docket No. CPAC 1017-6
Appl. No. 10/632,553

PATENT

Amendments to the Specification

Please replace paragraph [0002] with the following amended paragraph:

[0002] This application is related to U.S. Application No. (Atty Docket No. CPAC.1017-2) 10/632,549, titled "Semiconductor multi-package module having wire bond interconnection between stacked packages"; U.S. Application No. (Atty Docket No. CPAC.1017-3) 10/632,568, titled "Semiconductor multi-package module having package stacked over ball grid array package and having wire bond interconnection between stacked packages"; U.S. Application No. (Atty Docket No. CPAC.1017-4) 10/632,551, titled "Semiconductor multi-package module having wire bond interconnect between stacked packages and having electrical shield"; U.S. Application No. (Atty Docket No. CPAC.1017-5) 10/632,552, titled "Semiconductor multi-package module having package stacked over die-up flip chip ball grid array package and having wire bond interconnect between stacked packages"; U.S. Application No. (Atty Docket No. CPAC.1017-7) 10/632,550, titled "Semiconductor multi-package module including stacked-dic packages and having wire bond interconnect between stacked packages". This application and all the said related applications are being filed on the same date, and each of the said related applications is hereby incorporated herein by reference.